



# Material Composition Declaration

## EPC2034

Company Name	Efficient Power Conversion (EPC)	Issue Date:	3/14/2018
Contact Name:	Yanping Ma	Contact Title:	VP Quality
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Part Weight:	18.7 mg	Type of Product:	eGaN FET

Construction Element	Substance	CAS No. If Applicable	Weight (mg)	Mass (%)	Sum (%)	Mass (ppm)
Chip	Silicon	7440-21-3	13.9274	74.6704	77.7509	746704
	Silicon oxide	7631-86-9	0.0746	0.4000		4000
	Silicon nitride	12033-89-5	0.0272	0.1457		1457
	Gallium nitride	25617-97-4	0.1284	0.6883		6883
	Aluminum	7429-90-5	0.1431	0.7673		7673
	Aluminum nitride	24304-00-5	0.0379	0.2033		2033
	Titanium	7440-32-6	0.0029	0.0153		153
	Titanium nitride	25583-20-4	0.0122	0.0656		656
	Copper	7440-50-8	0.0048	0.0256		256
	Tungsten	7440-33-7	0.0032	0.0170		170
	Polyimide		0.1403	0.7524		7524
Under Bump Metal	Titanium	7440-32-6	0.0017	0.0091	0.7686	91
	Nickel	7440-02-0	0.0000	0.0000		0
	Vanadium	7440-62-2	0.0000	0.0000		0
	Copper	7440-50-8	0.1417	0.7595		7595
Solder Bump	Tin	7440-31-5	3.8262	20.5139	21.4805	205139
	Silver	7440-22-4	0.1603	0.8592		8592
	Copper	7440-50-8	0.0200	0.1074		1074
Sum in total:			18.6519	100.0000	100.0000	1000000

**Note:**

The substance content disclosed herewith is approximate and is based on engineering calculation. Statements are based on our present knowledge and may subject to change at any time due to technical requirements and development. EPC may update this document without notification. Statement may not include information regarding the minute quantities of dopant and metal materials in the electrical devices contained within the finished product.